



Material Composition Declaration

EPC2103

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	23.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	19.9310	86.6356	89.2948	866356
	Silicon oxide	7631-86-9	0.0891	0.3871		3871
	Silicon nitride	12033-89-5	0.0322	0.1400		1400
	Gallium nitride	25617-97-4	0.1029	0.4473		4473
	Aluminum	7429-90-5	0.1605	0.6978		6978
	Aluminum nitride	24304-00-5	0.0248	0.1080		1080
	Titanium	7440-32-6	0.0039	0.0171		171
	Titanium nitride	25583-20-4	0.0144	0.0626		626
	Copper	7440-50-8	0.0053	0.0232		232
	Tungsten	7440-33-7	0.0055	0.0237		237
	Polyimide		0.1731	0.7522		7522
Under Bump Metal	Titanium	7440-32-6	0.0015	0.0065	0.5504	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1251	0.5439		5439
Solder Bump	Tin	7440-31-5	2.2310	9.6978	10.1548	96978
	Silver	7440-22-4	0.0934	0.4062		4062
	Copper	7440-50-8	0.0117	0.0508		508
Sum in total:			23.0055	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.